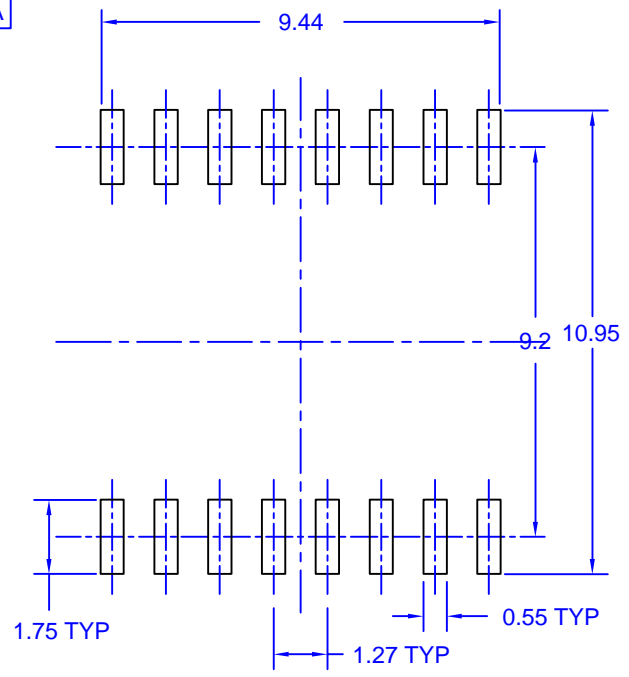
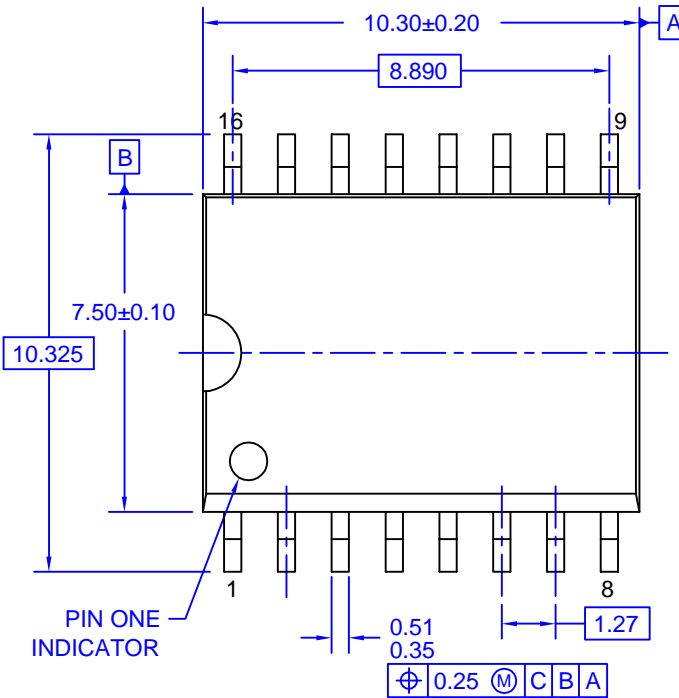


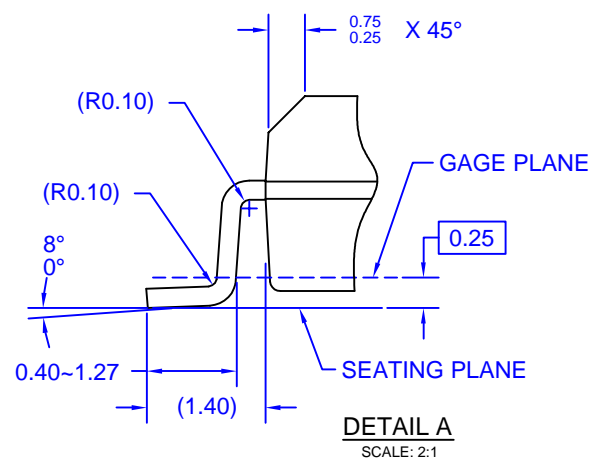
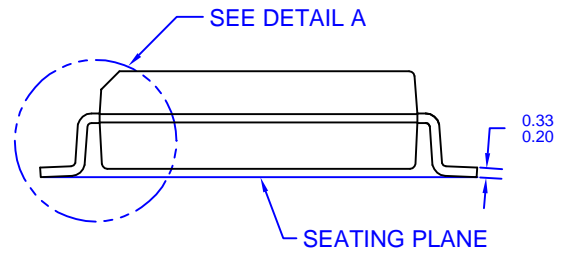
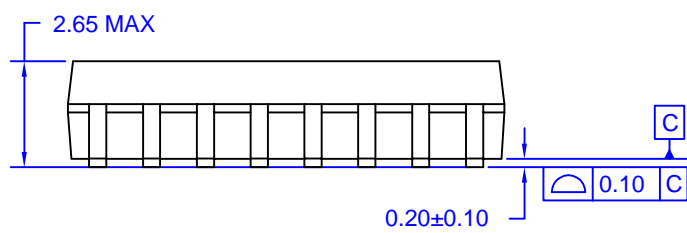
THIS DRAWING IS THE PROPERTY OF FAIRCHILD SEMICONDUCTOR CORPORATION. NO USE THEREOF SHALL BE MADE OTHER THAN AS A REFERENCE FOR PROPOSALS AS SUBMITTED TO FAIRCHILD SEMICONDUCTOR CORPORATION FOR JOBS TO BE EXECUTED IN CONFORMITY WITH SUCH PROPOSALS UNLESS THE CONSENT OF SAID FAIRCHILD SEMICONDUCTOR CORPORATION HAS PREVIOUSLY BEEN OBTAINED. NO PART OF THIS DRAWING SHALL BE COPIED OR DUPLICATED OR ITS CONTENTS DISCLOSED. THE INFORMATION CONTAINED ON THIS DRAWING IS CONFIDENTIAL AND PROPRIETARY.

REVISIONS

LTR	DESCRIPTION	E.C.N.	DATE	BY/APPD
F	NEW MARKING DWG.		Jan-1999	FEITAN
2	UPDATED DWG. TO CURRENT STD. FORMAT.		13-Mar-2007	J.Chen



LAND PATTERN RECOMMENDATION



NOTES: UNLESS OTHERWISE SPECIFIED

- A) THIS PACKAGE CONFORMS TO JEDEC MS-013, ISSUE E, DATED SEPT 2005.
- B) ALL DIMENSIONS ARE IN MILLIMETERS.
- C) DIMENSIONS DO NOT INCLUDE MOLD FLASH OR BURRS.
- D) LANDPATTERN STANDARD: SOIC127P1030X265-16L
- E) DRAWING FILENAME: MKT-16Brev2

M16BREV2

DETAIL A
SCALE: 2:1

APPROVALS		DATE	FAIRCHILD SEMICONDUCTOR	
DRAWN	J Chan	09 Mar 07	Bayan Lepas, FIZ, 11900, Penang, Malaysia.	
DFTG. CHK.			16LD, SOIC, JEDEC MS-013, 0.300" WIDE BODY	
ENGR. CHK.			SCALE	SIZE
			N/A	C
			DRAWING NUMBER	REV
			MKT-M16B	2
PROJECTION			DO NOT SCALE DRAWING	SHEET
				1 of 1